

General Purpose Transistor PNP Silicon NST3906MX2

Features

 These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CEO}	-40	Vdc
Collector - Base Voltage	V _{CBO}	-40	Vdc
Emitter - Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous (Note 1)	Ic	-200	mAdc
Collector Current - Peak (Note 1)	I _{CM}	-800	mAdc

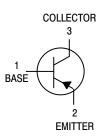
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Power Dissipation (Note 2) @ T _A = 25°C Derate above 25°C	P _D	165 1.39	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	720	°C/W
Total Power Dissipation (Note 3) @ T _A = 25°C Derate above 25°C	P _D	590 4.93	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 3)	$R_{\theta JA}$	203	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

- 1. Reference SOA Curve
- 2. Surface-mounted on FR4 board using a 0.6 mm², 2 oz. Cu pad
- 3. Surface-mounted on FR4 board using a 100 mm², 2 oz. Cu pad

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MARKING DIAGRAM



AF = Specific Device Code M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
NST3906MX2T5G	X2DFN3 (Pb-Free)	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Charac	teristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS		"			•
Collector – Emitter Breakdown Voltage (I _C = -1.0 mAdc, I _B = 0)		V _{(BR)CEO}	-40	_	Vdc
Collector – Base Breakdown Voltage ($I_C = -10 \mu Adc, I_E = 0$)		V _{(BR)CBO}	-40	_	Vdc
Emitter – Base Breakdown Voltage ($I_E = -10 \mu Adc, I_C = 0$)		V _{(BR)EBO}	-5.0	_	Vdc
Base Cutoff Current ($V_{CE} = -30 \text{ Vdc}$, $V_{EB} = -3.0 \text{ Vdc}$)		I _{BL}	-	-50	nAdc
Collector Cutoff Current (V _{CE} = -30 Vdc, V _{EB} = -3.0 Vdc)		I _{CEX}	-	-50	nAdc
ON CHARACTERISTICS (Note 4)		•			
$\begin{array}{c} \text{DC Current Gain} \\ \text{(I}_{\text{C}} = -0.1 \text{ mAdc, V}_{\text{CE}} = -1.0 \text{ Vdc)} \\ \text{(I}_{\text{C}} = -1.0 \text{ mAdc, V}_{\text{CE}} = -1.0 \text{ Vdc)} \\ \text{(I}_{\text{C}} = -10 \text{ mAdc, V}_{\text{CE}} = -1.0 \text{ Vdc)} \\ \text{(I}_{\text{C}} = -50 \text{ mAdc, V}_{\text{CE}} = -1.0 \text{ Vdc)} \\ \text{(I}_{\text{C}} = -100 \text{ mAdc, V}_{\text{CE}} = -1.0 \text{ Vdc)} \\ \text{(I}_{\text{C}} = -100 \text{ mAdc, V}_{\text{CE}} = -1.0 \text{ Vdc)} \end{array}$		H _{FE}	60 80 100 60 30	- 300 - -	-
Collector – Emitter Saturation Voltage ($I_C = -10 \text{ mAdc}$, $I_B = -1.0 \text{ mAdc}$) ($I_C = -50 \text{ mAdc}$, $I_B = -5.0 \text{ mAdc}$)		V _{CE(sat)}	_ _	-0.25 -0.4	Vdc
Base – Emitter Saturation Voltage $(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$ $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$		V _{BE(sat)}	-0.65 -	-0.85 -0.95	Vdc
SMALL-SIGNAL CHARACTERISTICS		•			
Current – Gain – Bandwidth Product ($I_C = -10 \text{ mAdc}, V_{CE} = -20 \text{ Vdc}, f$	= 100 MHz)	f _T	250	_	MHz
Output Capacitance (V _{CB} = -5.0 Vdc, I _E = 0, f = 1.0 M	Hz)	C _{obo}	-	4.5	pF
Input Capacitance (V _{EB} = -0.5 Vdc, I _C = 0, f = 1.0 M	Hz)	C _{ibo}	-	10	pF
Input Impedance ($I_C = -1.0 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$,	f = 1.0 kHz)	h _{ie}	2.0	12	kΩ
Voltage Feedback Ratio ($I_C = -1.0 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$,	f = 1.0 kHz)	h _{re}	0.1	10	X 10 ⁻⁴
Small – Signal Current Gain (I _C = -1.0 mAdc, V _{CE} = -10 Vdc, f = 1.0 kHz)		h _{fe}	100	400	-
Output Admittance ($I_C = -1.0 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)		h _{oe}	3.0	60	μmhos
Noise Figure (I _C = -100 μ Adc, V _{CE} = -5.0 Vdc, R _S = 1.0 k Ω , f = 1.0 kHz)		NF	-	4.0	dB
SWITCHING CHARACTERISTICS		•	•	•	•
Delay Time	(V _{CC} = -3.0 Vdc, V _{BE} = 0.5 Vdc,	t _d	_	35	m-
Rise Time	$I_C = -10 \text{ mAdc}, I_{B1} = -1.0 \text{ mAdc})$	t _r	-	35	ns
Storage Time	$(V_{CC} = -3.0 \text{ Vdc}, I_{C} = -10 \text{ mAdc},$	t _s	_	225	ns
Fall Time	$I_{B1} = I_{B2} = -1.0 \text{ mAdc}$	t _f	-	75	115

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

TYPICAL CHARACTERISTICS

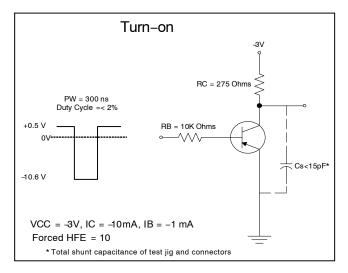
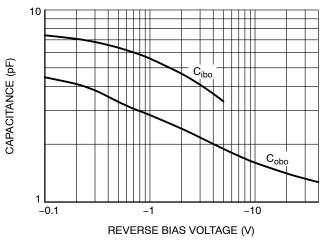


Figure 1. Delay and Rise Time Equivalent Test Circuit

Figure 2. Storage and Fall Time Equivalent Test Circuit



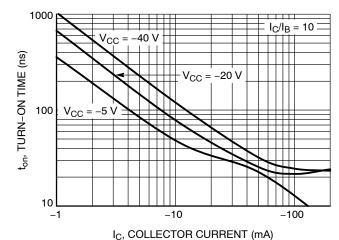
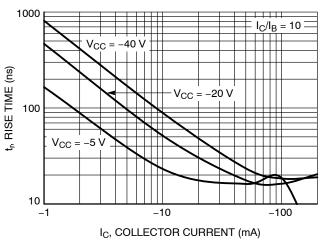


Figure 3. Capacitance

Figure 4. Turn-On Time



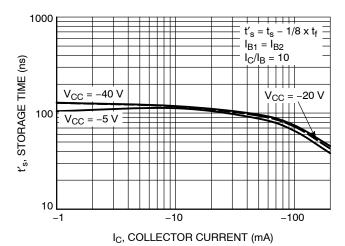


Figure 5. Rise Time

Figure 6. Storage Time

TYPICAL CHARACTERISTICS

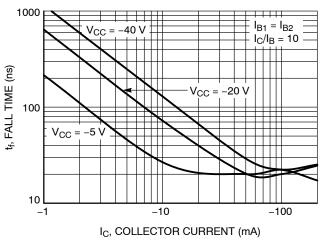


Figure 7. Fall Time

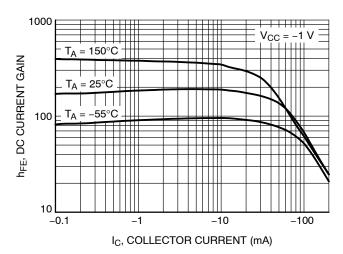


Figure 8. DC Current Gain

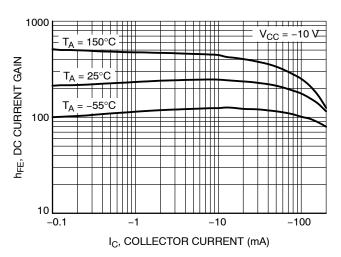


Figure 9. DC Current Gain

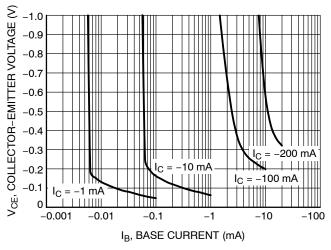


Figure 10. Collector Saturation Region

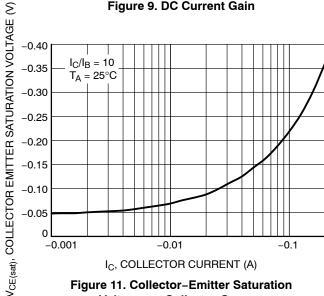


Figure 11. Collector-Emitter Saturation Voltage vs. Collector Current

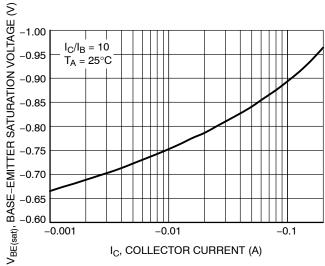


Figure 12. Base-Emitter Saturation Voltage vs. **Collector Current**

TYPICAL CHARACTERISTICS

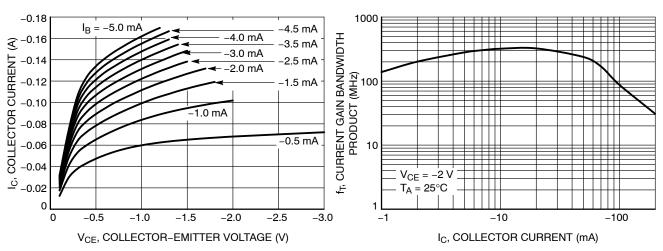


Figure 13. Collector Current vs. Collector-Emitter Voltage

Figure 14. Current Gain Bandwidth vs. Collector Current

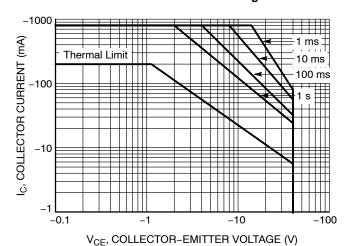
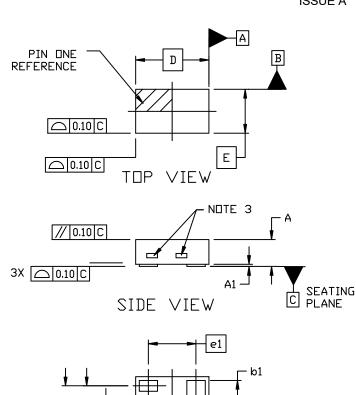


Figure 15. Safe Operating Area

PACKAGE DIMENSIONS

X2DFN3 1.0x0.6, 0.35PCASE 714AC ISSUE A



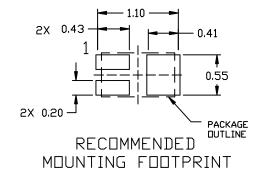
3X L

BOTTOM VIEW



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. EXPOSED COPPER ALLOWED AS SHOWN.
- 4. ALL PAD LOCATIONS CONTROLLED WITH THIS POSITIONAL TOLERANCE.

	MILLIMETERS		
DIM	MIN.	MAX.	MAX.
Α	0.34	0.37	0.40
A1	0.00		0.05
b	0.10	0.15	0.20
b1	0.45	0.50	0.55
D	0.95	1.00	1.05
Е	0.55	0.60	0.65
е	0.35 BSC		
e1	0.65 BSC		
L	0.20	0.25	0.30



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NOTE 4

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